

WHAT IS CLAIMED IS:

1. A method for forming a solder resist pattern comprising the steps of:

5 pre-treating both sides of a double-sided printed circuit board;

laminating a semi-cured thermosetting film on the both sides of the printed circuit board; and

10 irradiating a laser beam to the laminated thermosetting film according to a solder resist mask pattern to selectively remove the thermosetting film, the solder resist mask pattern having been previously designed prior to irradiating.

15 2. The method for forming a solder resist pattern according to claim 1, wherein the pretreatment includes scrubbing.

20 3. The method for forming a solder resist pattern according to claim 1, further comprising curing the semi-cured thermosetting film after laminating the thermosetting film.

4. A method for forming a solder resist pattern comprising the steps of:

25 pretreating a portion exposed from a plurality of layers constituting a multilayer printed circuit board fabricated by

buildup process;

laminating a thermosetting film on the pretreated portion; and

irradiating a laser beam to the laminated thermosetting film according to a solder resist mask pattern to selectively
5 remove the thermosetting film.

5. The method for forming a solder resist pattern according to claim 4, wherein the pretreatment includes
10 scrubbing.

6. The method for forming a solder resist pattern according to claim 5, further comprising curing the semi-cured thermosetting film after laminating the thermosetting film.
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7. A method for forming a solder resist pattern comprising the steps of:

pretreating a portion exposed from a plurality of layers constituting a multilayer printed circuit board fabricated in
20 a parallel manner;

laminating a thermosetting film on the pretreated portion; and

irradiating a laser beam to the laminated thermosetting film according to a solder resist mask pattern to selectively
25 remove the thermosetting film.

8. The method for forming a solder resist pattern according to claim 7, wherein the pretreatment includes scrubbing.

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9. The method for forming a solder resist pattern according to claim 8, further comprising curing the semi-cured thermosetting film after laminating the thermosetting film.

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